



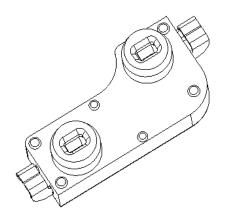


# **Document Number:**

KH-PS1607-10

# 产品规格书

# Product Specification



<u>P/IN:</u>		
	CPG151101S11	

Title:

#### 1511 Connector

Rev.	ECN	Release and Revision Description:	Prepared By /Date:	Checked By/Date:	Approved By/Date:
A		New releasing 初版发行	罗衡军/2016/03/15	胡远峰/2016/03/15	陈军/2016/03/15
В		Revise format 修订格式	汤佳 2016/11/25	胡远锋 2016/11/25	易平 2016/11/25





# **Product Specification**

**P/N: DOC. No.:** CPG151101S11 KH-PS1607-10

Rev.:

**Page:** 2/9

# Content

目:	录	
1.	Scope/范围:	3
2.	Product Application/产品应用:	3
3.	Technology Parameters/技术参数	3
4.	Ratings/额定性能要求	3
5.	Profile Dimensions /外形尺寸	4
6.	Electrical Performance/电气性能	5
7.	Mechanical Performance/机械性能	6
8.	Environmental Performance/环境性能	7
9.	Recommended PCB Layout/推荐的 PCB 安装焊盘规格	8
10.	Packaging/包装	8
11.	Precaution/注意事项	9





 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG151101S11
 KH-PS1607-10
 B
 3/9

#### 1. Scope/范围:

This Product Specification covers the requirement of Mechanical keyboard Connector switch on product performance, test methods and quality assurance provisions.

本规格书内容涵盖机械键盘连接器产品的要求,包括性能指标、测试方法及质量保证方面等。

#### 2. Product Application/产品应用:

Mainly applied on computer keyboards, cash registers equipment and Man-Machine interface.

主要适用于电脑, 收银机, 工业设备和人机界面

#### 3. Technology Parameters/技术参数

Ambient Humidity 工作湿度:

Operating Temperature Range 使用温度范围:

Storage Temperature Range 保存温度范围:

Normal Condition:

Ambient temperature 环境温度:

Relative humidity 相对湿度:

Air pressure 气压:

Contact Resistance 接触阻抗:

Solder Ability 可焊性:

Withstand Soldering Temperature 耐焊接热:

45~95% R.H.:

-10℃~+60℃;

-20℃~+70℃:

**20**±2℃

85% ± 5% R.H.;

86~101KPa:

100 m  $\Omega$  Max:

 $260\pm5^{\circ}$ ,  $3\pm0.5$ s;

260±5 $^{\circ}$ C,5±1s;

#### 4. Ratings/额定性能要求

Rating Voltare 额定电压:

Rating Current 额定电流

InsulationResistance 绝缘电阻:

Withstand Voltage 耐电压:

Mechanical Life 机械寿命:

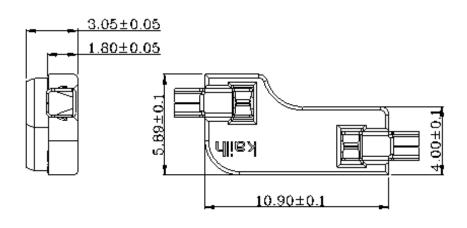
12V AC/DC max; 2V DC min 10mA AC/DC max; 10uA DC min

 $\geq$ 100M $\Omega$ /DC 500V;

AC 100V 1 Minute;

100Cycles (No lead).

#### 5. Profile Dimensions /外形尺寸





# **Product Specification**

**P/N: DOC. No.:** CPG151101S11 KH-PS1607-10

**Rev.:** Page: 4/9

#### 6. Electrical Performance/电气性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
6.1	Contact Resistance 接触电阻	Static load: (Operation force)x2, which is applied on the center of Switch stem. 静态负载:动作力的 2 倍,施加在手柄中心.  Measurement tool: Contact resistance Meter. 测量工具:微电流接触电阻计(1KHz, 20mV,5~50mA)	100mΩ Max 100mΩ以下
6.2	Insulation Resistance 绝缘电阻	Apply a Voltage of DC 500 V for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 500V DC 电压 1 分钟,按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.	100MΩ Min 100 兆欧以上
6.3	Dielectric withstanding voltage 耐电压	Apply a Voltage of AC 100 V (50~60Hz) for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 100V AC 电压 1 分钟, 按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.	No evidence of breakdown 无瞬断、击穿等破坏.

#### 7. Mechanical Performance/机械性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求	
7.1	Mating force 插入力	At 16in/minute.actuation speed	Mating force 插入力 3KG max	



<b>Product</b>		Specif	icatio	n
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 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG151101S11
 KH-PS1607-10
 B
 5/9

7.2	Unmating force 拔出力	At 16in/minute.actuation speed	Unmating force 拔出力 200gf min
7.3	Shock 机械冲击	Measured by according to the below condition: (1) Acceleration: 80g 加速度 (2) Cycles of test:3 cycles each in 6 directions, for a total of 18 cycles. 试验次数:每个方向 3 次,6 个方向共 18 次.	Appearance: No abnormality. 外观无异常
7.4	Life Test 寿命测试	<ul> <li>(1) No load 无负载</li> <li>(2) Mating force: Maximum value of operation force. 插入力: 操作力规格值的上限.</li> <li>(3) Cycles: 100 Min 操作次数: 100 次以上</li> </ul>	Contact resistance: 200 m Ω Max 接触电阻: 200 毫欧以下 Bouncing: 10ms Max

#### 8. Environmental Performance/环境性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
8.1	Cold test 耐寒性	(1) Temperature: - 20±2℃ 温度: - 20±2℃ (2) Duration of test: 48h 持续时间: 48 小时 (3) Take off a drop water 去掉水珠 (4) Standard conditions after test: 1h 试验后的放置条件: 1 小时	Contact resistance: 200m Ω Max 接触电阻 200m Ω以下



### 凱華電子 KAIHUJA EELETBONIGS

**Product Specification** 

 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG151101S11
 KH-PS1607-10
 B
 6/9

8.2	Heat test 耐热性	<ul> <li>(1) Temperature: 70±2℃</li> <li>温度: 70±2℃</li> <li>(2) Duration of test: 48h</li> <li>持续时间: 48 小时</li> <li>(3) Take off a drop water 去掉水珠</li> <li>(4) Standard conditions after test: 1h</li> <li>试验后的放置条件: 1 小时</li> </ul>	Contact resistance: 200m Ω Max Shall meet: No. 6.2 接触电阻 200m Ω以下 满足: No. 6.2
8.3	Temperature cycle 温度循环	(1) Test cycles:20 cycles 试验周期: 5 个周期 (2) Standard condition after test:1h 试验后的放置条件: 1 小时  Temperature Duration of test 持续时间 20±5℃ 1h -20±5℃ 1h -20±5℃ 1h 60±5℃ 1h 70±5℃ 1h	Contact resistance: 200m Ω Max Shall meet: No. 6.2 接触电阻 200m Ω以下 满足: No. 6.2
8.4	Soldering heat test 耐焊接热	Soldering area: T/2 of PWB thickness. (PWB: T=1.6mm) 焊接面积: 印刷基板的 1/2 厚度处 Soldering temperature: 260±5℃ Soldering time: 3±0.5s 焊接温度: 260±5℃ 焊接时间: 3±0.5 秒	Appearance: No abnormality. 外观无异常
8.5	Solderability 可焊性	<ol> <li>Hand soldering 手工焊接: Please practice according to below condition:         <ol> <li>Soldering Temperature: 350±5℃ 焊接温度: 350±5℃</li> <li>Continual soldering time: 3±0.5s 连续焊接时间: 3±0.5 秒</li> <li>Capacity of soldering iron: ≤20w 电烙铁功率: 20 瓦以下</li> </ol> </li> <li>Automatic Reflow soldering 自动回流焊接: For the product of SMT, according to below condition:</li> </ol>	At least 90% of surface area of immersed portion shall be covered by solder. 侵焊面积大于 90%以上.



**Product Specification** 

**P/N:**CPG151101S11

KH-PS1607-10

Rev.: Pa

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		SMT回流焊温度曲线图				
		230	时间	c Max.		
8.6	Humidity test 耐湿性	(1) Temperature: 60±2℃ 温度: 60±2℃ (2) relative humidity: 90~95% R.H. 相对湿度:90~95% R.H. (3) Duration of test: 48h 持续时间: 48 小时 (4) Take off a drop water 去掉水珠 (5) Standard conditions after test: 1h 试验后的放置条件: 1 小		Contact re 200m Ω I Shall mee No. 6.2 接触电阻 满足: No. 6.2	Max et :	
8.7	Salt Spray 盐雾测试	Apply the following environment to tell 根据下列条件进行测试:  (1) Temperature: 35±5℃ 温度: 35±5℃;  (2) Salt water density: 5±1% 盐水浓度: 5±1%;  (3) Duration: 12 hours 持续时间: 12 小时;  (4) After test, the salt deposit shall be removed by running water. 实验后将盐沉积物用水冲掉		Appearan No corros crack, no naked. 外观: 无原 无裸露基 Contact F 200 m Ω 接触电阻:	sion spot, base plat 爾蚀点,无 材. Resistance Max	ee 裂纹, e:



8.8

# 凱華電子 KAIHUA EELETRONICS

**P/N: DOC. No.:** CPG151101S11 KH-PS1607-10

Rev.: B

**Page:** 8/9

Withstand K<sub>2</sub>S 硫化测试 Apply the following environment to test: 根据下列条件进行测试

(1) Temperature: 35±5℃温度: 35±5℃

(2) K<sub>2</sub>S Density: 2%; 硫化钾浓度: 2%

(3) Duration: 2 minute. 持续时间: 2 分钟 Appearance: No corrosion spot, no crack, no base plate naked.

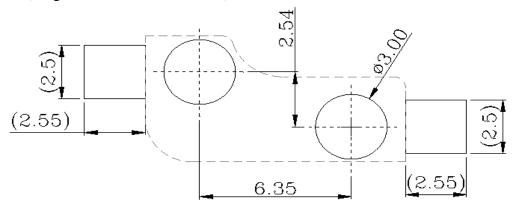
外观:无腐蚀点,无裂纹, 无裸露基材.

Contact Resistance:  $500 \text{ m} \Omega$  Max

接触电阻: 500毫欧以下

#### 9. Recommended PCB Layout 推荐的 PCB 安装焊盘规格

(Top View) (Single face board T=1.6mm)



PCB LAYOUT

#### 10. Packaging 包装

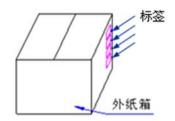
Packaging type: 13Tray, 26000Pcs/Carton.

包装方式:13/盘, 26000Pcs/箱.











### **Product Specification**

 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG151101S11
 KH-PS1607-10
 B
 9/9

#### 11.Precaution 注意事项

11.1 Soldering condition 回流焊条件

11.1 Soldering condition		
ITEM		CONDITION
项目		条件
Preheating zone 预热区	Heating zone 升温区	Speed<2℃/S, Preheating time15 S Max,temperture150℃ 速度<2℃/S, 预热时间 15 S 最多,温度 150℃
	Heatpreservati on area 保温区	Speed1. 2~3. 5℃/S,Preheating time120 S Max,temperture180℃ 速度 1. 2~3. 5℃/S,预热时间 120 S 最多,温度 180℃
	Fast heating zone 快速升温区	Speed3. 5~4. 5℃/S, Preheating time140 S Max,temperture230℃ 速度 3. 5~4. 5℃/S,预热时间 140 S 最多,温度 230℃
Weld area 焊接区		Welding time 40 S Max ,welding temperature peak value,3 sec Max. 焊接时间 40 S 最多,焊接温度峰值 260℃ 最大,3 S 最多
Area of flux 助焊剂面积		1/2 Max of PWB Thickness 印刷基板厚度的 1/2 以内
Temperature of solder 焊锡温度		260±5℃ 260±5℃
Number of soldering 焊接次数		2time Max (But should down heat of the first soldering) 2 次以内
Printed wiring board 印刷基板		Single side copper-clad laminates 单面铜箔

- (1) After reflow, be careful not to clean switches with solvent 回流焊后,注意不要用溶剂清洗.
- (2) Under the condition of using soldering iron, soldering temperature shall be 350℃ max within 3 sec. 在使用铬铁的情况下,焊锡温度应在350℃以下,焊接时间3秒以内.

#### 11.2 Notes 注意点

- (1) Please be cautious not to give excessive static load connector.
  - 注意不要施加超负荷的压力或晃动连接器.
- (2) Connector be careful not to stack up P. W. B. after switches were soldered. 连接器焊接以后,印刷基板注意不要叠放.
- (3) Preservation under high temperature and high humidity or corrosive gas should be avoided Especially. When you need to preserve for a long period, do not open the carton. 保管时尤其应注意避开高湿高温和有腐蚀性气体的环境.如需长时间保存,请不要打开包装箱.
- (4) Products meet the ROHS & REACH environmental management substances control standards 产品满足 ROHS & REACH 环境管理物质管制标准